

Disco DFG8560



Disco DFG8560 system is a 300mm capable, fully automatic in-feed surface grinder. Using the same basic layout as the DFG8540 grinder, this two-spindle, three-chuck design is capable of performing both large diameter and thin-finish grinding. The software and GUI interface are similar to the DFG8540.

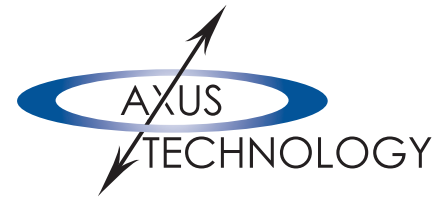
OPTIONS AVAILABLE

Temperature control system for stabilizing process results

Vacuum system

Integration with DBG

Integration with Disco polisher model DFP8140



Your source for leading-edge surface processing solutions

FEATURES

- Automated thinning up to 300mm diameter wafers
- Ultra-thin wafer handling to 100µm and less
- DBG option available and plasma-ready
- Flat/Notch alignment orientation
- Interior grind water nozzle
- Chuck/Spinner table
- Positioning and stopping system
- 2 air bearing grind spindles, 3 rotary-chuck tables